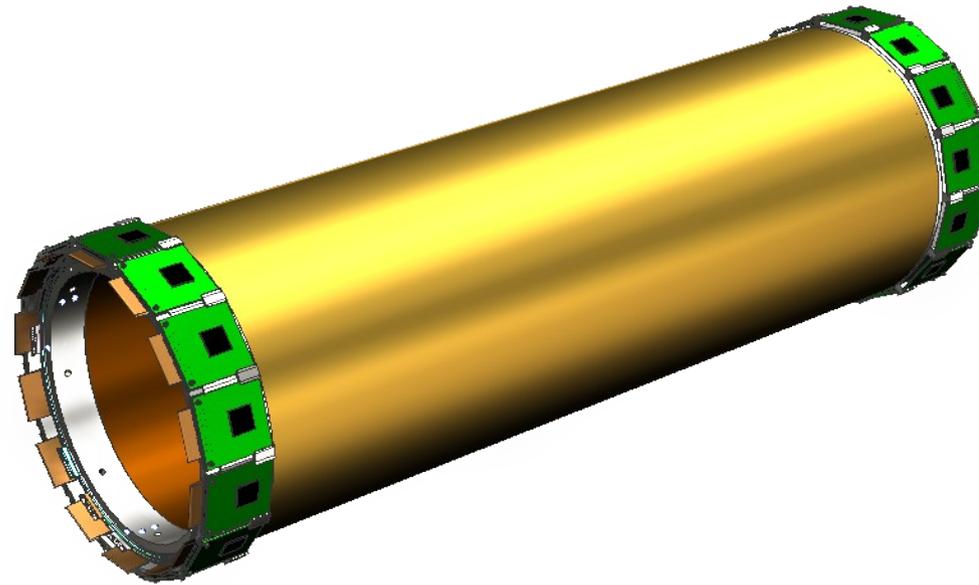


BESIII



Introduction to  
the Workshop CGEM FEE, trigger and DAQ  
for the BESIII experiment

Riccardo Farinelli

INFN Ferrara – University of Ferrara  
on behalf of the BESIIICGEM consortium  
Turin – 13-14 April, 2016



# Outline

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- The BESIII experiment
- The Cylindrical GEM-Inner Tracker
- Status of the project
  - Assembly of the first cylindrical layer
  - Measurement of the performance with a test beam
  - Status of electronics (not shown in this introduction)



# BESIII @ IHEP

- The Beijing Electron-Positron Collider BEPCII and the Beijing Spectrometer BESIII work at from 2 to 4.6 GeV

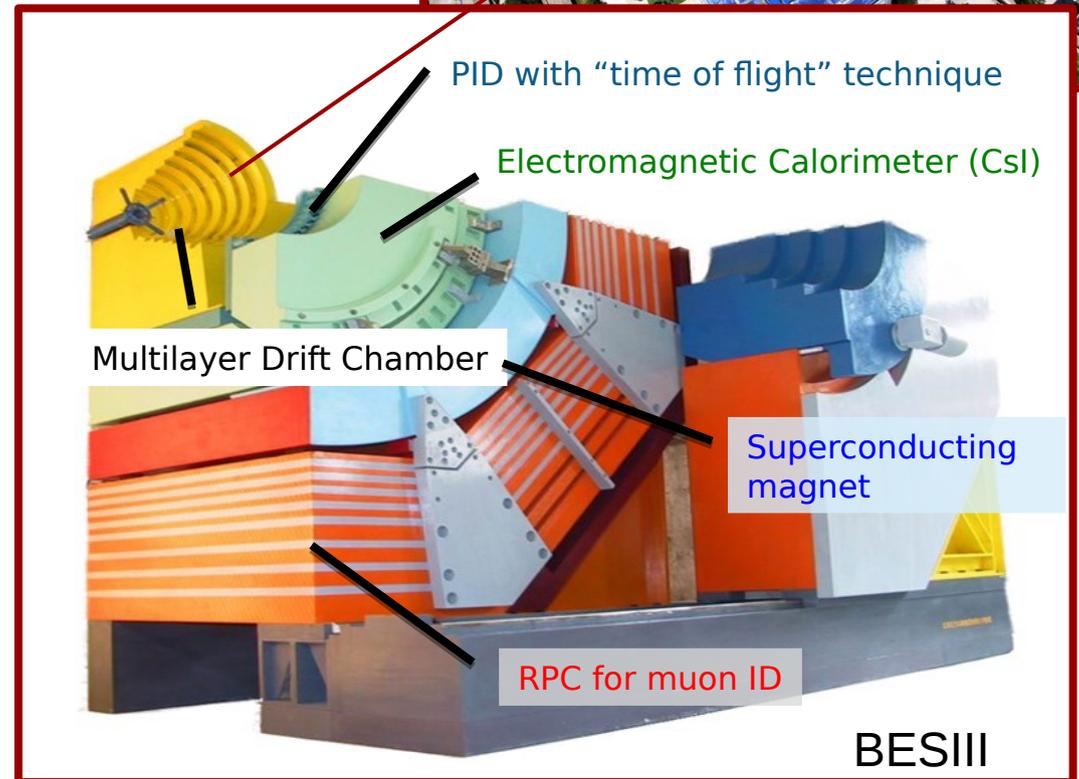
→  $E_{\text{cm}} = 2 - 4.6 \text{ GeV}$

→  $L_{\text{design}} = 10^{33} \text{ cm}^{-2}\text{s}^{-1}$

- **At least 7 more years of data taking**

- The physics program includes:

- High precision test of EW interaction
- High statistic studies of light hadron spectroscopy
- Studies of charm physics
- Studies of  $\tau$  physics
- 12 countries and 58 institutions



# The BESIII detector

A multipurpose magnetic spectrometer with an effective geometrical acceptance of 93% of  $4\pi$  is built up by a series of subdetectors

## Multilayer Drift Chamber

120  $\mu\text{m}$  spatial resolution  
 $dp/p \sim 0.5\%$  @ 1 GeV/c

## Time Of Flight

90 ps time resolution  
for PID

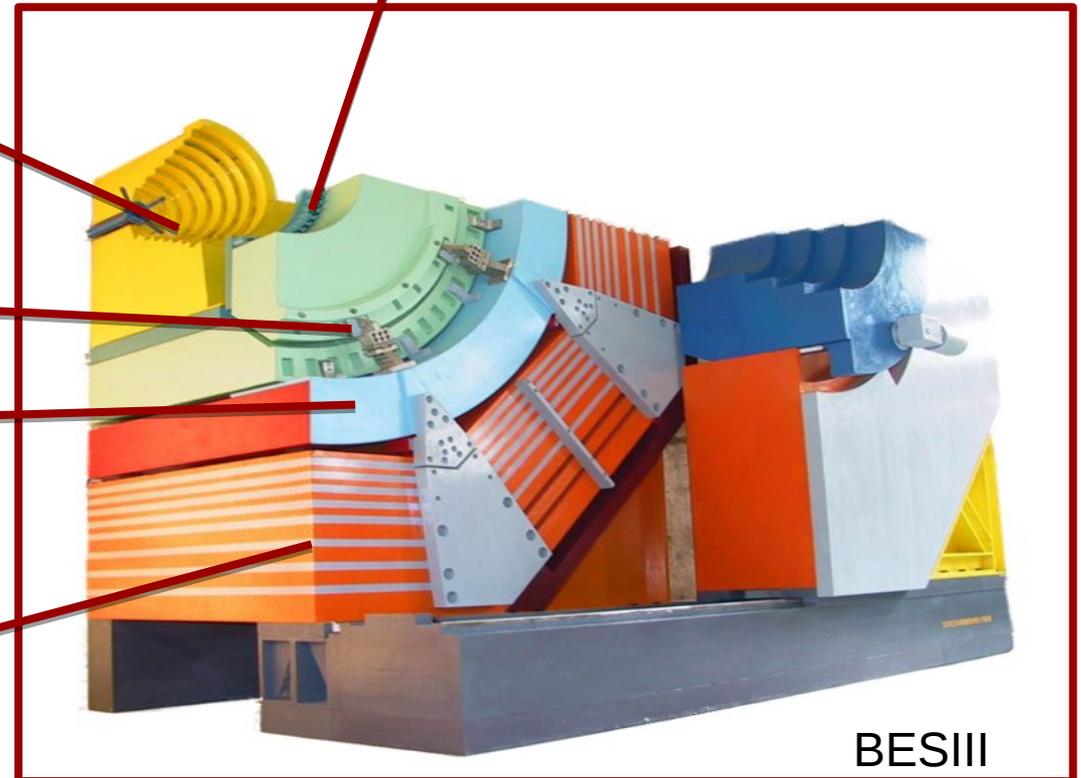
## Electromagnetic Calorimeter (CsI)

$dE/E \sim 2.5\%$  @ 1 GeV/c

## Superconducting magnet

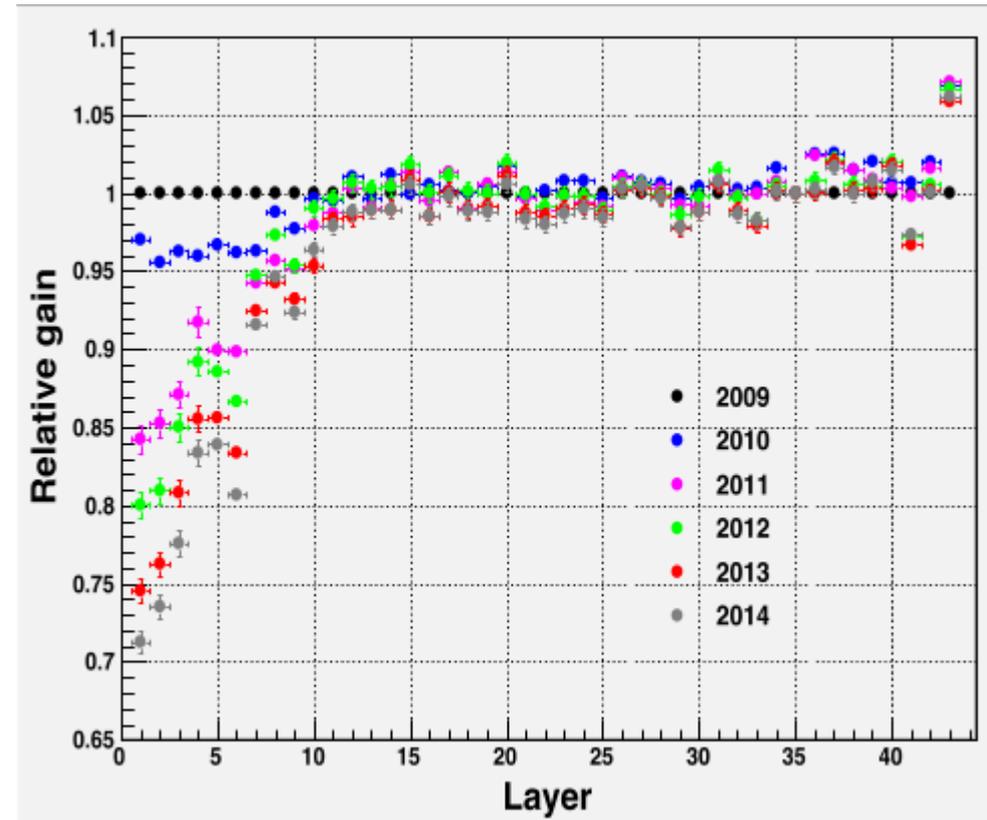
magnetic field = 1 Tesla

## RPC for muon ID



# MDC aging

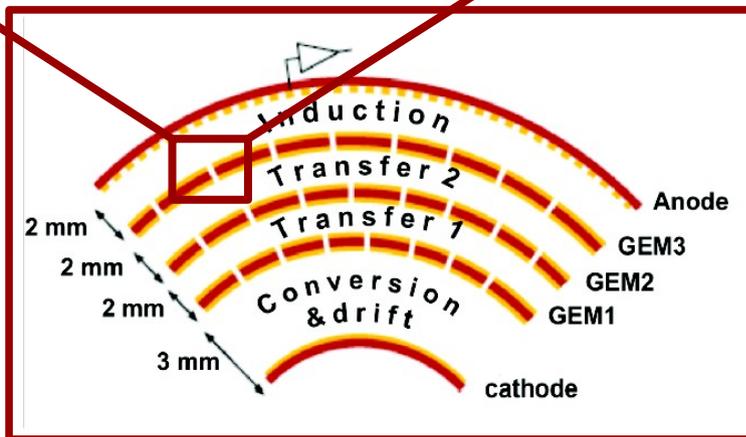
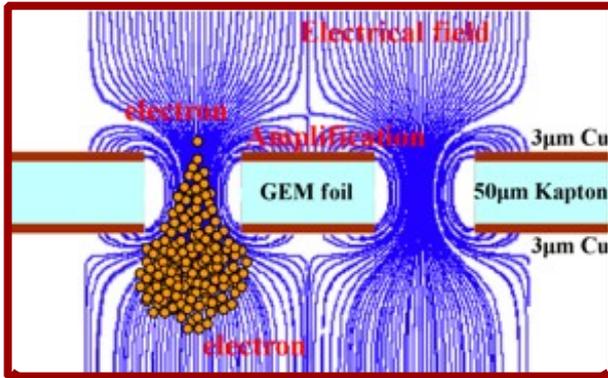
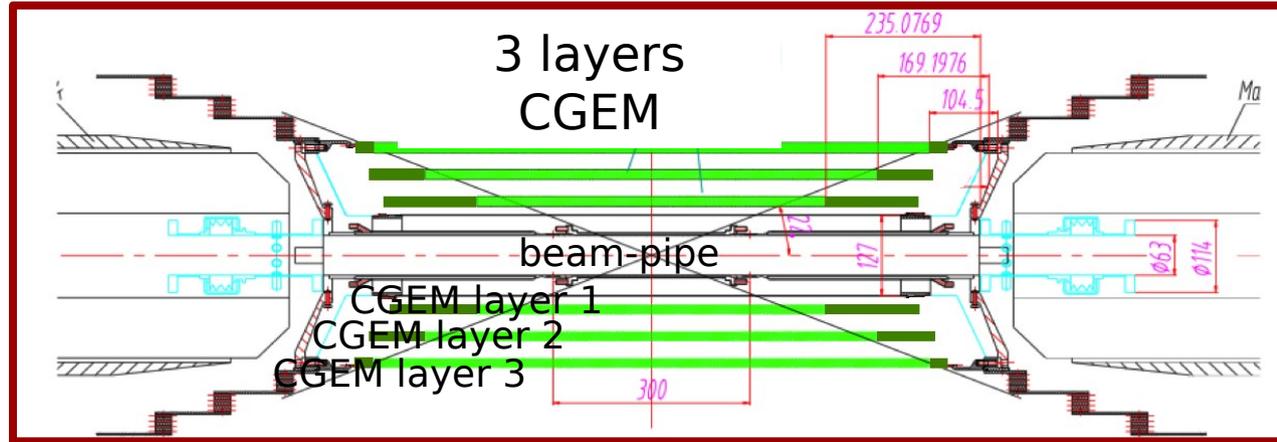
- The Multilayer Drift Chamber is built up by 43 layers and it shows a significant aging in the inner part
- The HV values of the MDC have been lowered to keep the current under control. This has worsened the reconstruction efficiency
- BESIII is an experiment that will take data until 2022 or more and it needs a new IT. The Italian group proposed to replace the inner part of the MDC with 3 independent layers of triple-GEM



# The Cylindrical GEM-IT

The project has been funded by the Foreign Affairs Ministry(MAE) and it received funded by the European Commission within the H2020-MSCA-RISE-2014

German, Swedish and Chinese collaborators joined the group and a CDR has been approved by the Executive Board in 2014



## Requirements

- Workability in a magnetic field of 1 Tesla
- Rate capability:  $\sim 10^4$  Hz/cm<sup>2</sup>
- Spatial resolution:  $s_{xy} \sim 120 \mu\text{m}$  :  $s_z \sim 1$  mm
- Momentum resolution:  $\sigma_{p_t}/P_t \sim 0.5\%$  @1GeV
- Efficiency =  $\sim 98\%$
- Material budget  $\leq 1.5\%$  of  $X_0$  all layers
- Coverage: 93%  $4\pi$
- Operation duration  $\sim 5$  years

Installation planned for 2018



# KLOE2 and improvement



- The KLOE-2 CGEM detector is the first one built and now it is normally taking data in the running experiment
  - Respect to the state of the art the CGEM-IT for BESIII will take advantage of these improvements:
    - Rohacell
    - Anode design
    - Analog and  $\mu$ TPC readout
- development of a dedicated ASIC

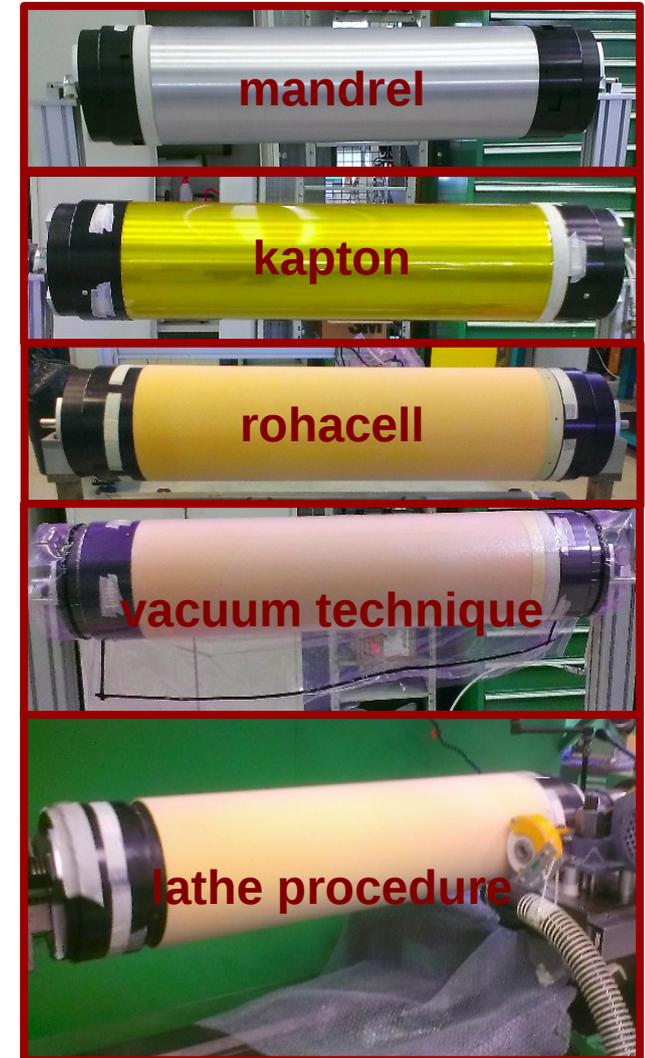
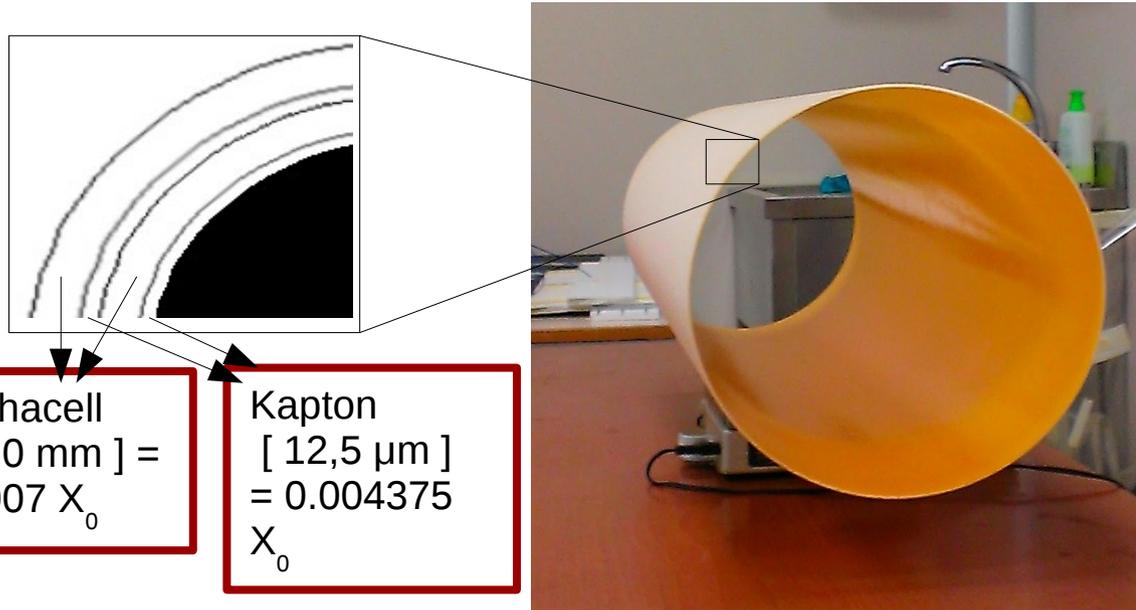
## Operational environment difference:

KLOE-2 →  $B = 0.5T$  / digital r.o. /  $s_{xy} = 200 \mu\text{m}$

BESIII →  $B = 1.0T$  / analog r.o. /  $s_{xy} = 120 \mu\text{m}$



# Anode and cathode construction



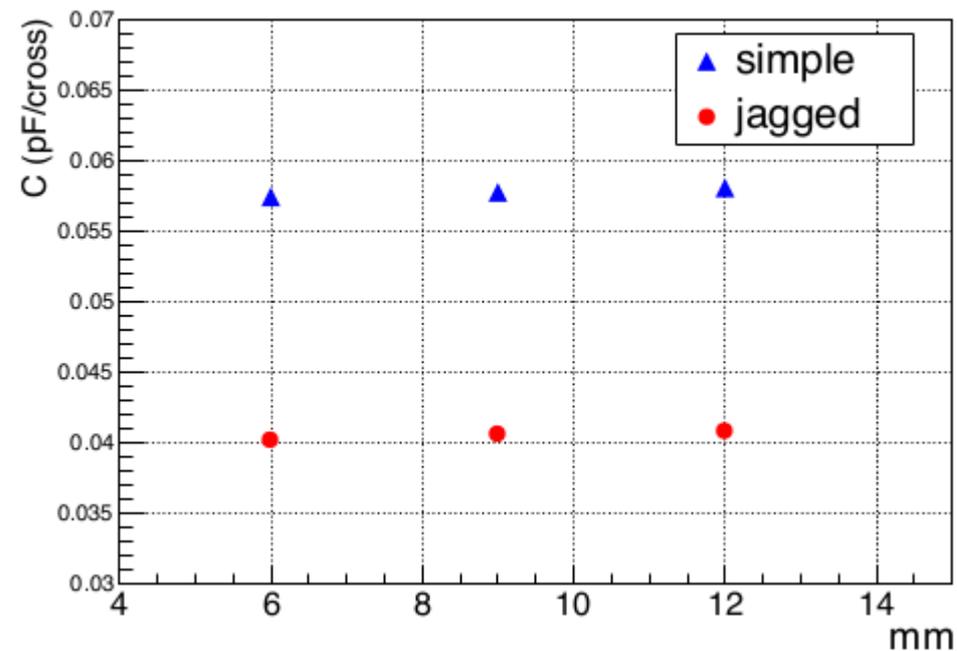
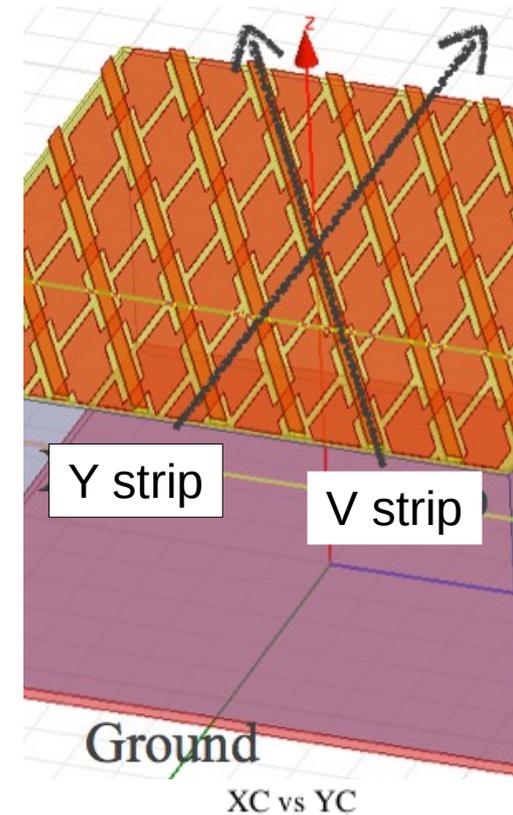
- Structure weight (without electrode) weight 180 g and  $0.02275 X_0$
- The full CGEM-IT material budget will be  $\sim 1\% X_0$
- Cathode electrode and anode circuit are build similarly and are glued onto a kapton - rohacell double sandwich
- The mechanical support is performed by annular flanges of permaglass placed on the edges of the cylinder



# Readout plane design and features

BESIII will deploy a readout with two set of strips and a stereo angle produced by TS-DEM department at CERN

- **large strip capacitance** up to 100-160 pF
- stereo angle depending on the layer geometry: about + 45°, - 30°, + 30°
  - **different stereo angles will help reducing the combinatoric**
- strip geometry is 650/570/130  $\mu\text{m}$
- (pitch, Y wide, V wide)
  - about 10'000 electronics channels
- ground plane at 4 mm from the readout
- **jagged strip layout studied to minimize the strip capacitance**

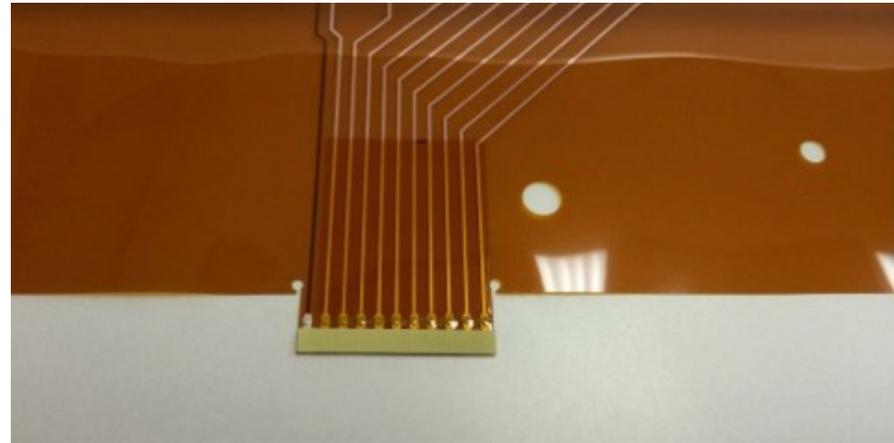
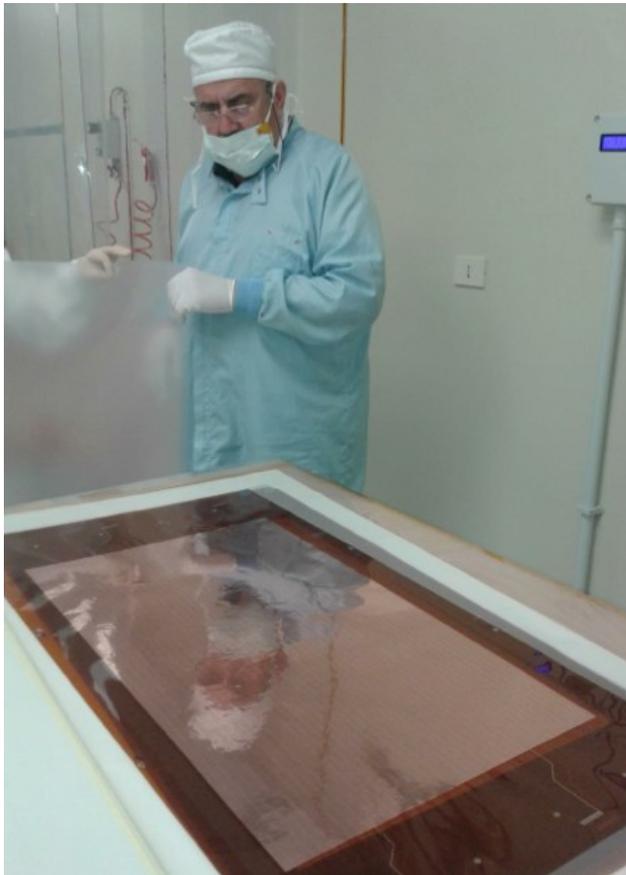


# Construction of the first cylindrical layer



# GEM test

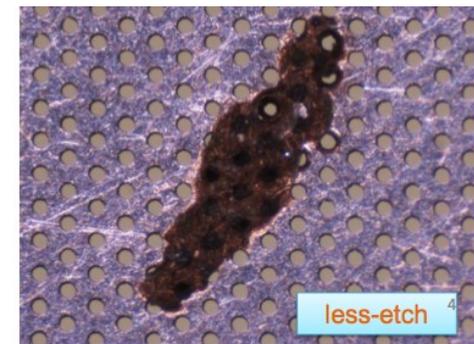
GEM foils arrived from CERN and have been tested in the clean room.



GEM production quality test.  
Before gluing, a HV test is performed on the GEM foils.

Good GEM must satisfy both:

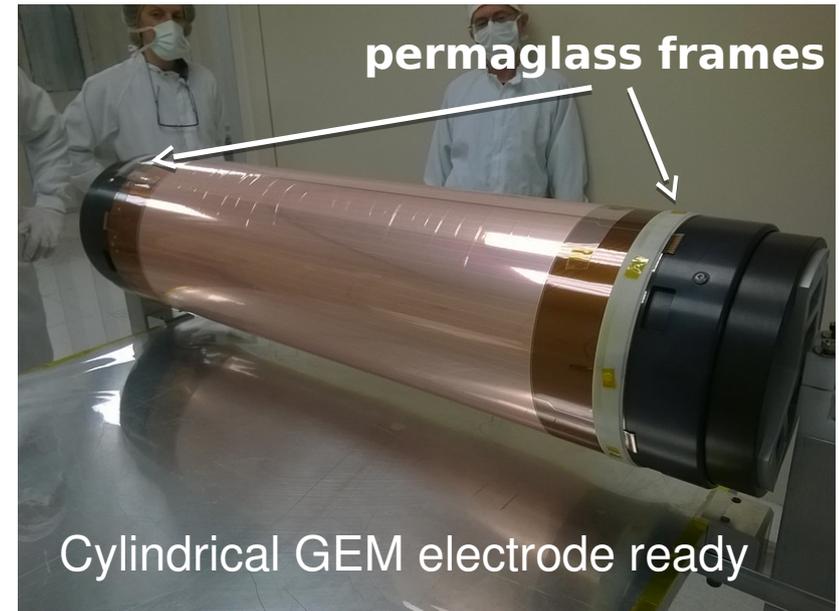
- $<1 \text{ nA @ } 600 \text{ V}$
- $<2 \text{ discharges/30mins}$



# GEM assembly



- The mechanical precision of all the items involved is critical for the detector assembly.
- Main issue of the gluing procedure is the mechanical tolerance of the reference holes used for the foils alignment.



# Cathode and anode test and assembly

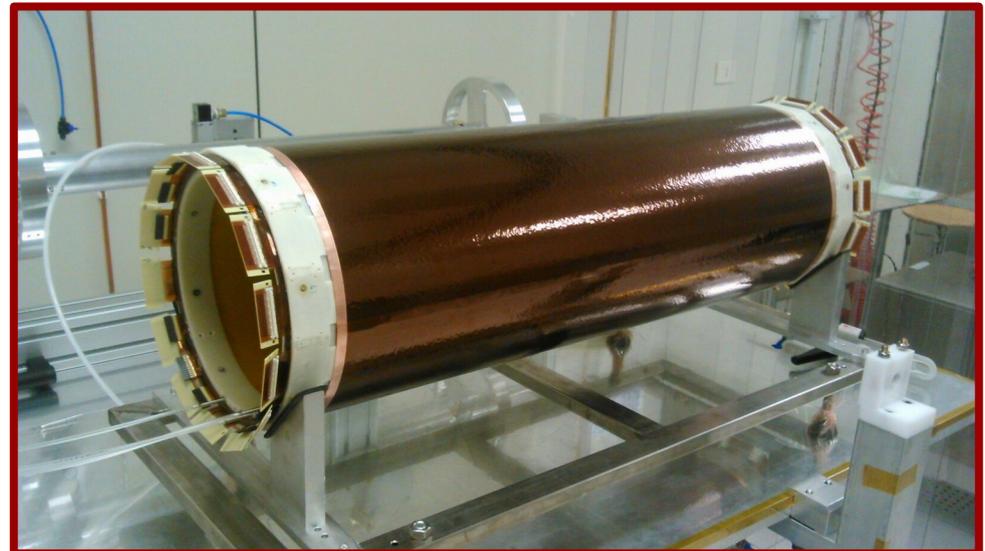
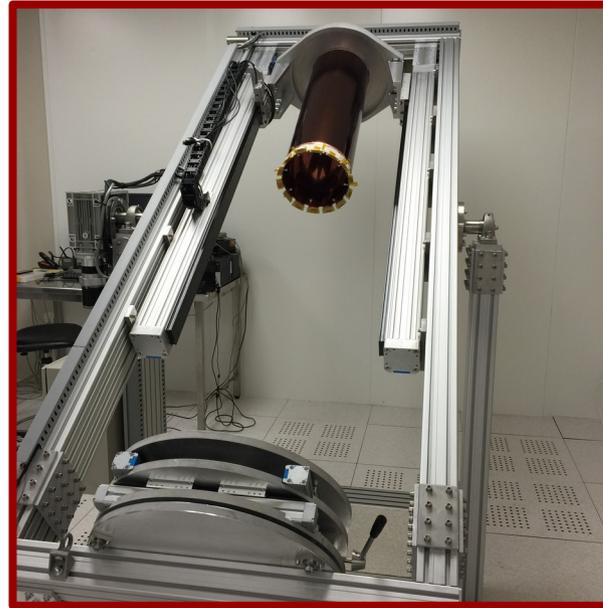
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- Several deformation test on the mechanical structure have been performed:
  - axial compression before and after an irradiation test
  - internal pressure variation
- Cathode and anode electrodes are glued to the rohacell/kapton structure and thanks to the glue and the vacuum technique the cylindrical form is fixed



# Assembly

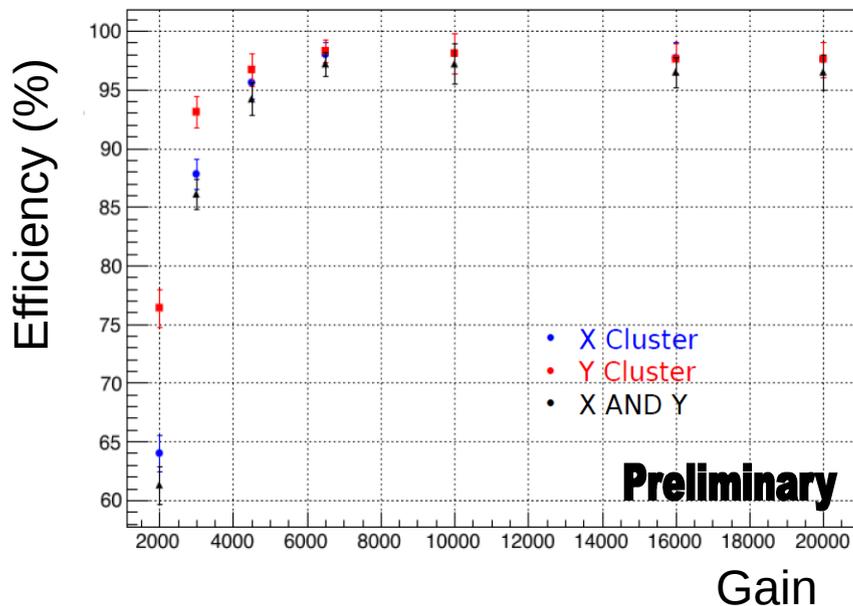
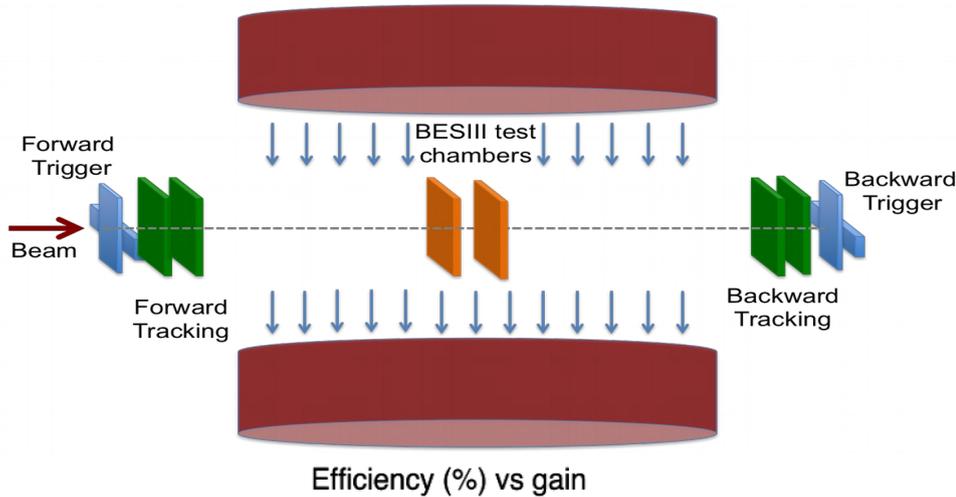
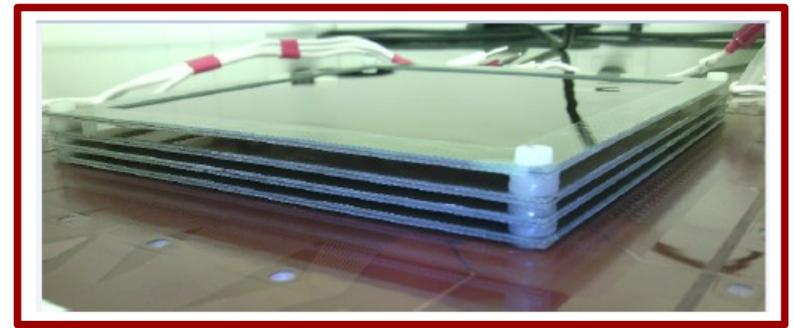
- Once the 5 electrodes (3 GEM, cathode and anode) have been built, they are assembled concentrically
- Axial alignment has a precision of  $100\mu\text{m}$  along the operational length of 1.5m
- A dedicated assembling machine has been designed and realized to perform the insertion of the electrodes
- The structure can rotate by  $180^\circ$  around its central horizontal axis
- The first Cylindrical prototype of triple-GEM has been successfully assembled and now is under test



# Measurement of the performance



# TestBeam of a planar triple GEM prototype



Several planar triple-GEM prototypes have been tested in a testbeam @ H4-CERN to:

- Validate analogue and  $\mu$ TPC readout
- Validate Garfield simulations
- Test different gas mixtures and geometries

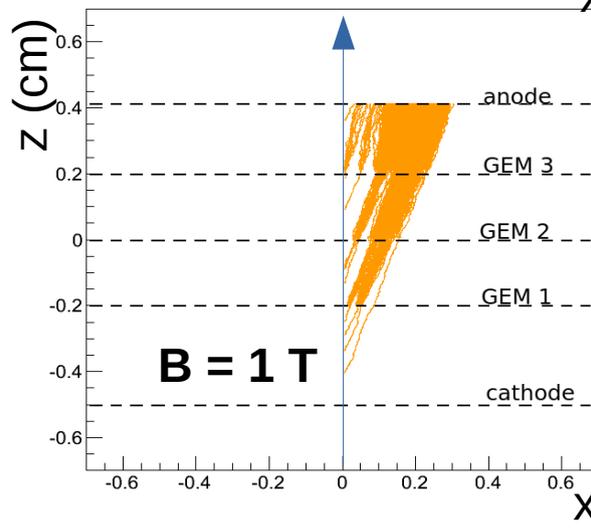
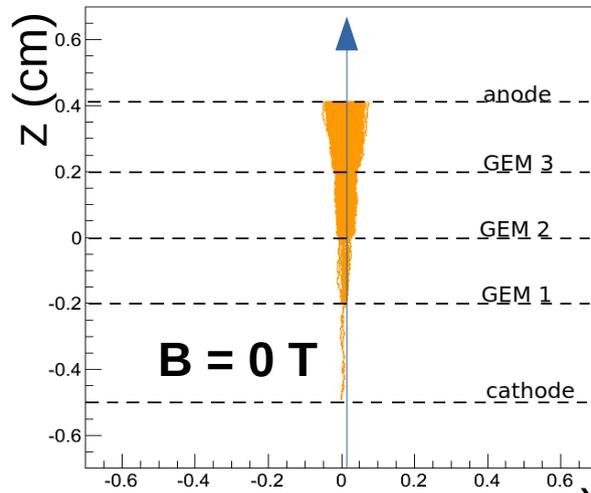
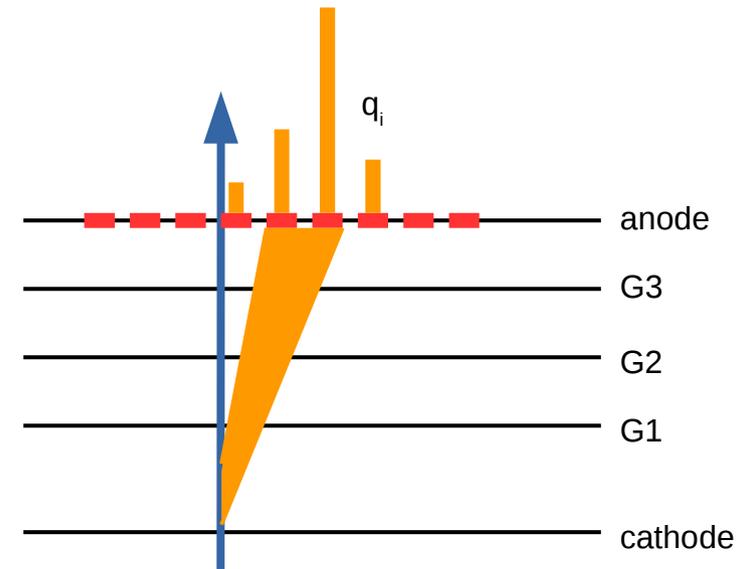
Efficiency plateau starts at  $\sim 6000$ . The efficiency on both the view is  $\sim 97\%$ .

A pitch of  $650\mu\text{m}$  has been used with a gas mixture of Argon-Isobutane (90/10) and Ar- $\text{CO}_2$  (70/30).

The spatial resolution reached **without magnetic field** is below of  $100\mu\text{m}$  with the charge centroid method.



# Magnetic field effect on the electron avalanche



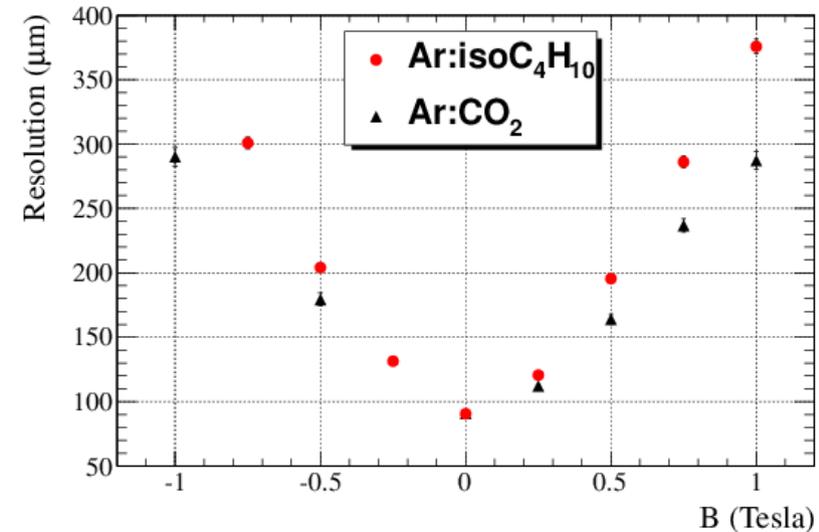
- The magnetic field acts on the electron avalanche and its effect has been studied with Garfield simulation

➤ The Lorentz force shifts the avalanche,

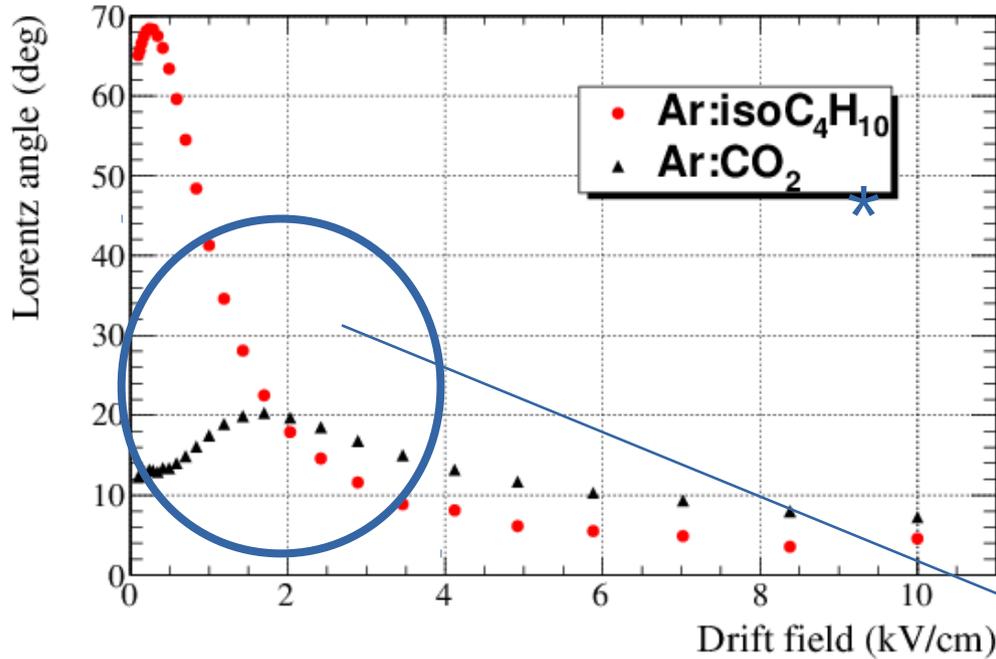
➤ Additionally the magnetic field **B** enlarge the charge distribuion collected at the anode;

➤ The shape of the charge distribution is no longer gaussian and the charge centroide.

$$x = \frac{\sum x_i * q_i}{Q_{TOT}}$$

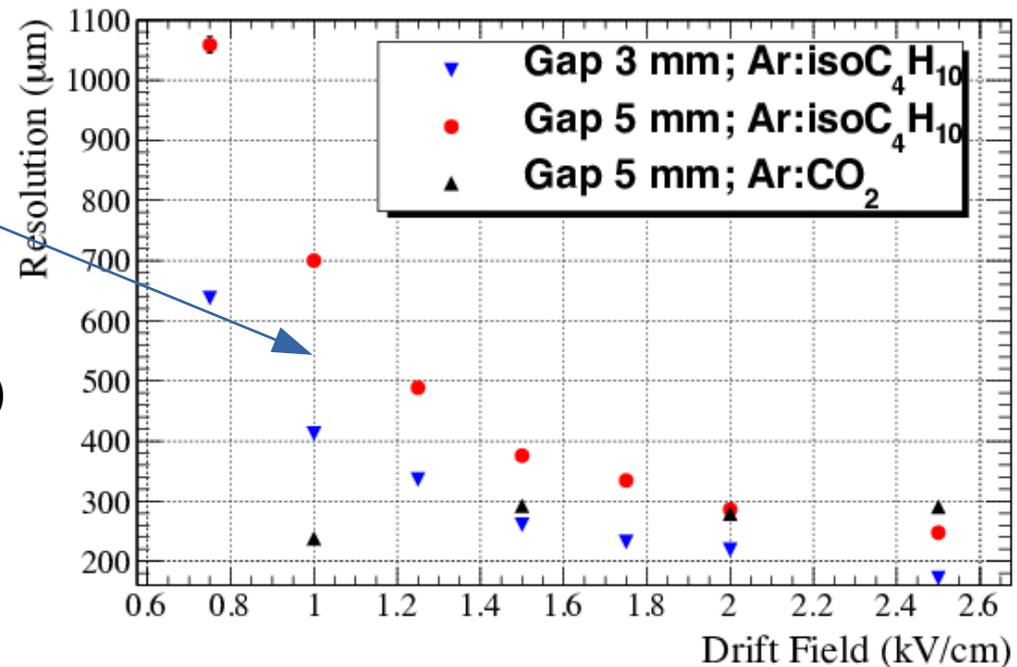


# Optimization of the prototype @ 1 Tesla



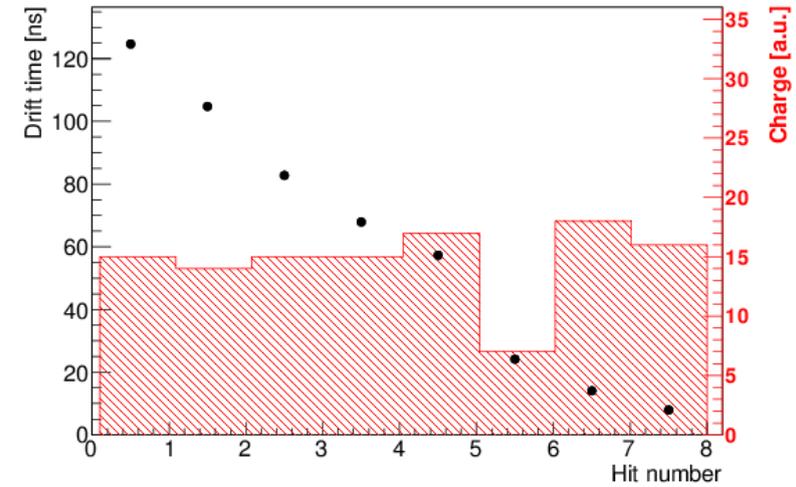
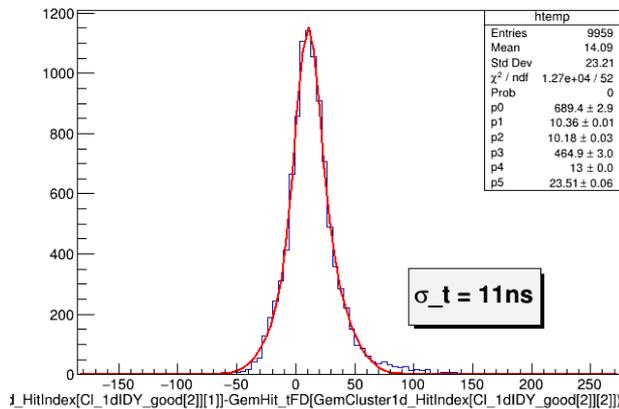
- The prototype with Argon-Isobutane (90/10) gas mixture and high drift field reaches the spatial resolution of  $\sim 190\mu\text{m}$  with a magnetic field of 1T
- The efficiency is constant if this range of field values

- The behavior of the spatial resolution and the Lorentz angle are similar.
- The loss of the charge centroid performance is mainly due to the increasing of the Lorentz angle

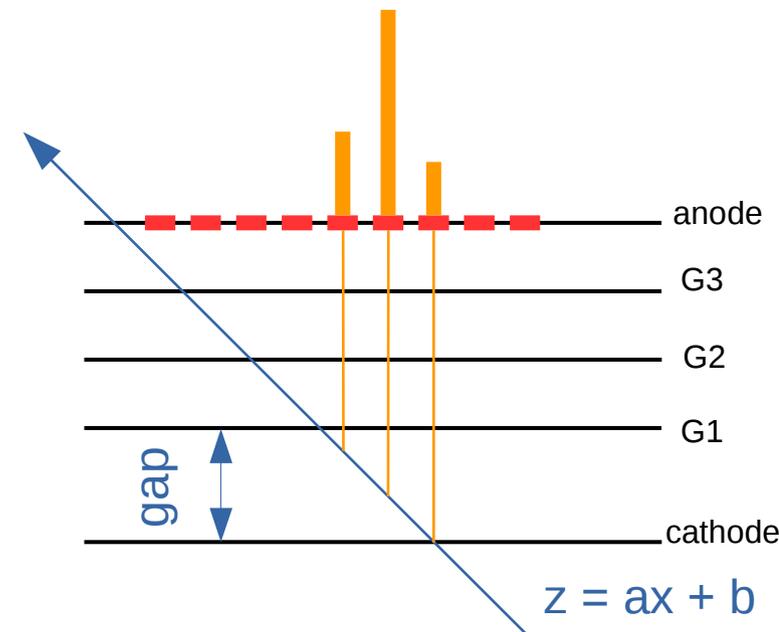


# μTPC method

- The time information can be used to improve the spatial resolution in magnetic field and in case of non-perpendicular tracks.
- The time resolution measured is 11 ns. This take into account the contribution of the detector and electronics.
- The new ASIC has to have good timing performance.
- Known the drift velocity, it is possible to assign to each fired strip a bi-dimensional point. These points are used to reconstruct the track in the conversion region
- The method is initially tested with **angled tracks and without magnetic field**



$$x = \frac{\frac{gap}{2} - b}{a}$$



# $\mu$ TPC results

The charge centroid resolution increases linearly with the incident angle of the track because the number of fired strips increases and the charge distribution as well

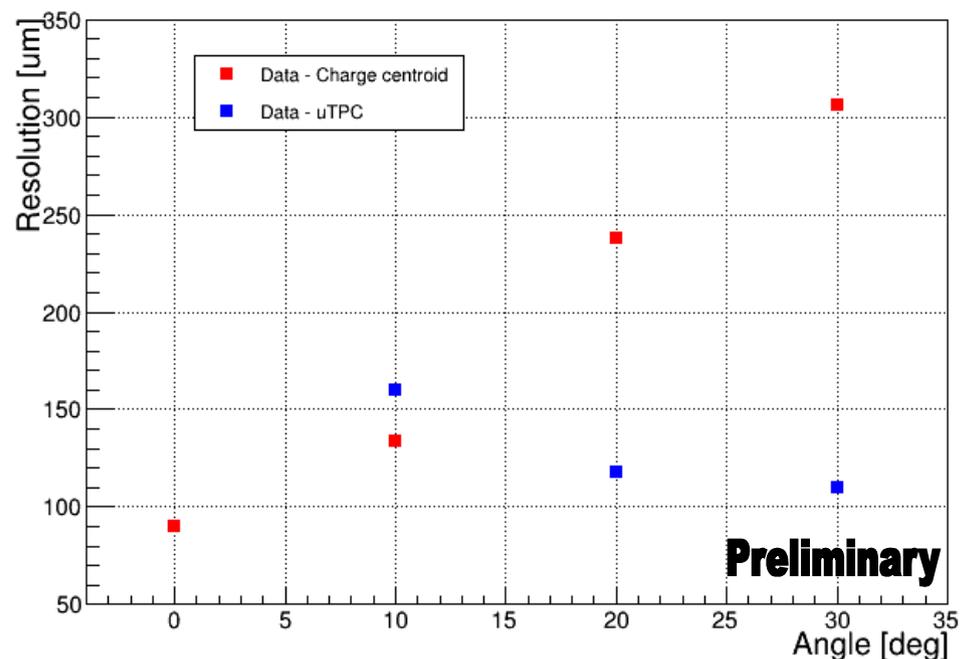
The  $\mu$ TPC allows to reconstruct angled tracks without lose of performance:

- At angles greater that  $10^\circ$  the resolution is flat around  $\sim 130\mu\text{m}$
- At angles smaller that  $10^\circ$  the number of fired strip is too small to apply successfully this method

The incident angle of the track is reconstructed in  $\mu$ TPC and the angular resolution improve at the increasing of the angle

The shown results are measured **without magnetic field and with angled tracks**

→ we expect a similar behavior in magnetic field because the Lorentz angle is  $\sim 26^\circ$  (Ar/Iso)

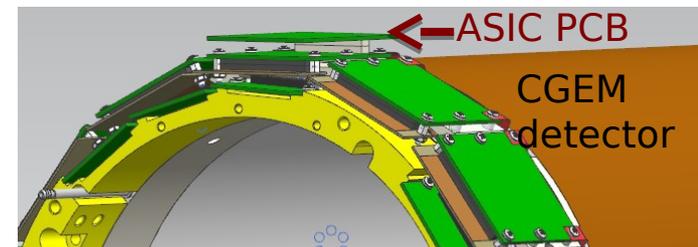


# Some numbers about the ASIC



# Frontend electronics

- **The analog readout** is mandatory to limit the number of electronics channels. The charge measurements is performed by a dedicated ASIC chip.
  - with moderate strip pitch ( $650\ \mu\text{m}$ )  $\sim 10000$  electronics channels  
64 channels per ASIC  $\rightarrow$  2 ASIC in each frontend PCB  $\rightarrow$  80 PCB
  - ASIC PCBs will be located on the detector to preserve the S/N ratio
- **Design of CGEM ASIC** (UMC  $.11\ \mu\text{m}$ ) starting from existing design (IBM  $.13\ \mu\text{m}$ )
  - BackEnd design shared by several projects
  - BackEnd porting to UMC  $.11\ \mu\text{m}$  in progress
  - Different input stage (suited for CGEM) to increase signal sensitivity and SNR
- **FrontEnd Optimization**
  - input stage optimized to handle capacitance in the range  $20\text{pF}$ - $100\text{pF}$



# Main feature of the ASIC design

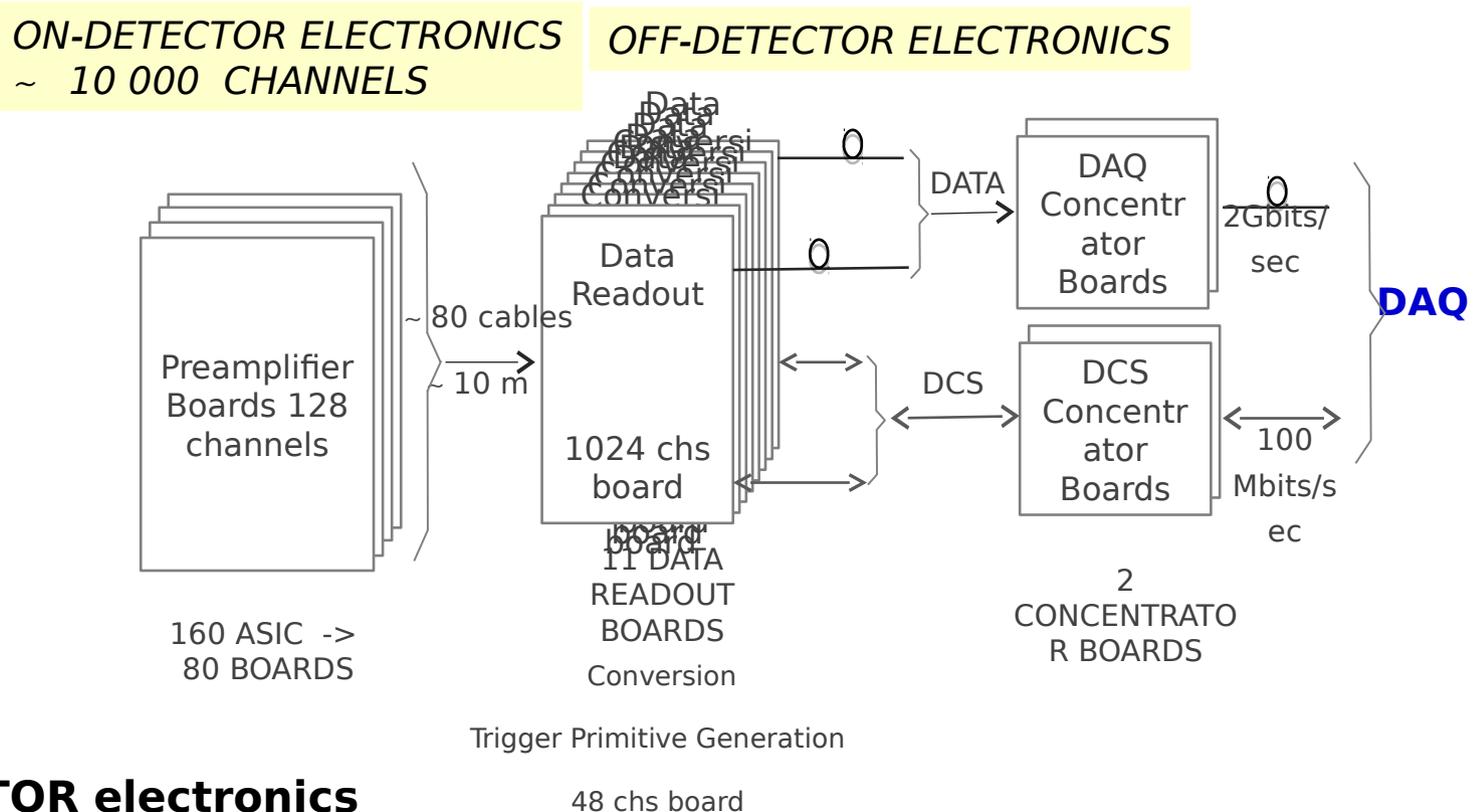
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- UMC 110 nm technology (limited power consumption, **to be tested for radiation tolerance**)
- Input charge: 1-50 fC
- Maximum sensor capacitance 100 pF
- Input rate: 60 kHz/channel
- Time and Charge measurements by independent TDCs
- TDC time binning  $> 50$  ps
- Time resolution: 4-5ns  $\Rightarrow$  **CGEM needed time resolution  $\sim 5$  ns**
- Double threshold discrimination
- Analog to Digital Converter (ADC) to measure the charge
- Power consumption  $\sim 10$  mW p/channel feasible  $\Rightarrow$  **about 100W in total**



# CGEM electronics

## FEE Architecture inherited by KLOE-2 experiment



- **ON-DETECTOR electronics**  
Preamp boards located on the detector to preserve the S/N ratio
- **OFF-DETECTOR electronics**  
Readout boards and Concentrator boards as close as possible to the detector

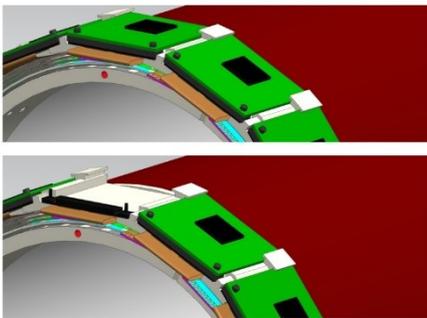
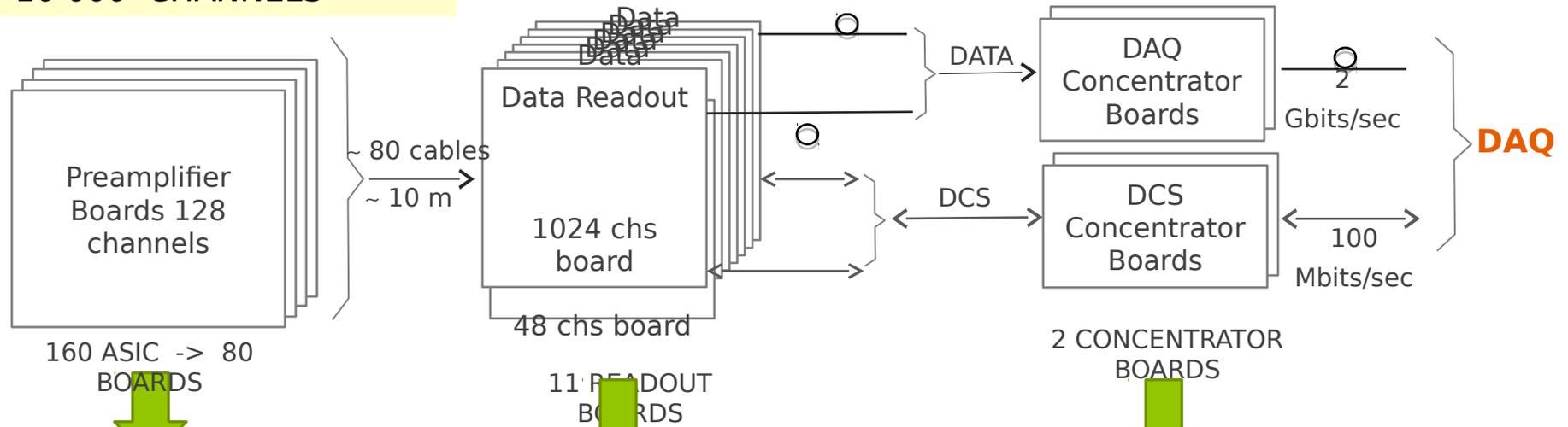


# CGEM electronics

## FEE BLOCK DIAGRAM

ON-DETECTOR ELECTRONICS  
~ 10 000 CHANNELS

OFF-DETECTOR ELECTRONICS



INFN-  
TORINO  
IHEP-  
China



INFN-  
FERRARA

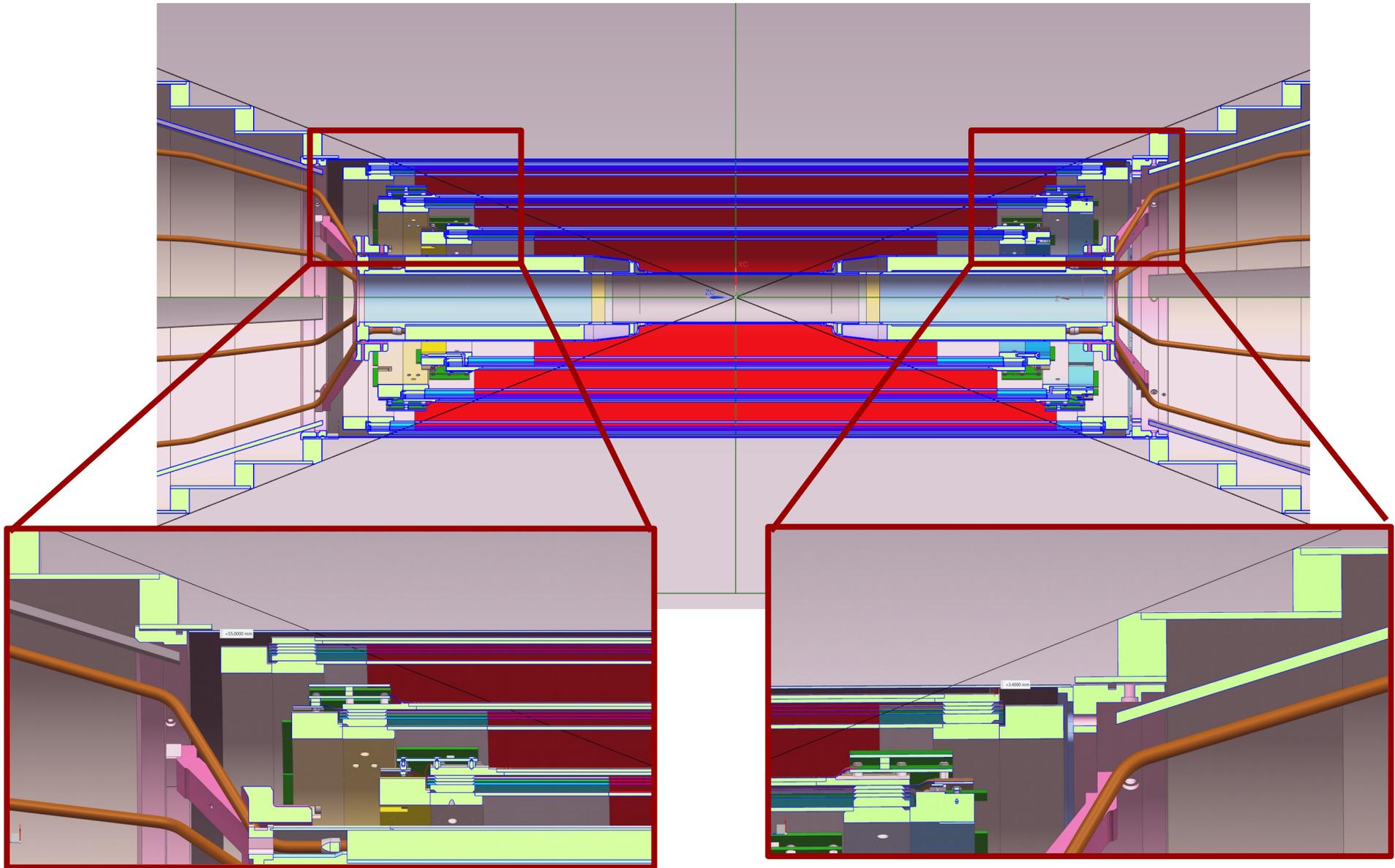
INFN-  
LNF



Uppsala  
U



# Free space



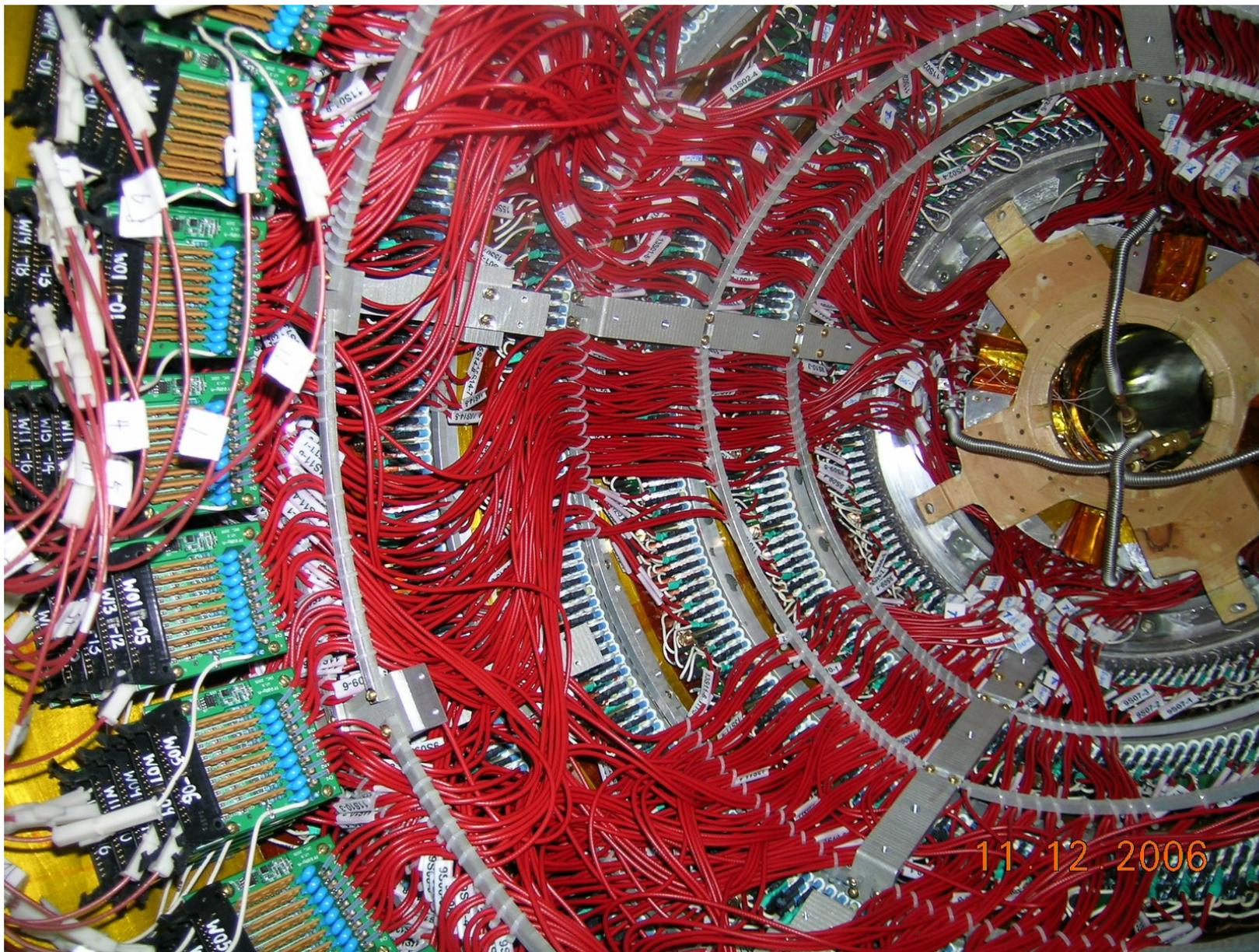
# Layer 3 issue

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- The layer 3 readout system is inside the active region
- At the current design the beam radiation would destroy the electronics and an alternative solution occurs
- Four possible solutions must be proposed here:
  - Re-make the flange
  - Increase the strip length and move the electronics away from the beam
  - Reduce the size of the electronics
  - Exchange the cathode plane with the anode



# Rooting cable



# Conclusion and future plans

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- A prototype of triple-GEM with charge centroid method has been optimized to work @ 1 Tesla and it reaches a spatial resolution of  $\sim 190\mu\text{m}$ : the best results in literature for GEM detector in magnetic field of 1 Tesla
- A first implementation of the  $\mu\text{TPC}$  readout system without magnetic field allows to reaches the BESIII requirement for angled tracks
- The feasibility of the  $\mu\text{TPC}$  in magnetic field is under development but preliminary results (not showed) confirm this tendency
- The first Cylindrical triple-GEM for BESIII has been successfully assembled and it will be tested in a testbeam after the gas and HV tests
- A new electronics for the CGEM-IT is under development. The BESIII geometry gives the main constrain while the reconstruction method feasibility impose its requirement



Thanks

